



Serial No. 09/754,323

Docket No.: 1081.1102

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of:

Masatoshi AKAGAWA

Serial No. 09/754,323

Confirmation No. 3680

Filed: January 5, 2001

Group Art Unit: 2823

Examiner: Scott A. Brairton

For: SEMICONDUCTOR DEVICE AND MANUFACTURING METHOD THEREFOR

AMENDMENT

Assistant Commissioner for Patents
Washington, D.C. 20231

Sir:

This is in response to the Office Action mailed December 19, 2003, and having a period for response set to expire on March 19, 2003.

The following amendments and remarks are respectfully submitted. Reconsideration of the claims is respectfully requested.

IN THE CLAIMS:

Please AMEND the following claims:

1. (TWICE AMENDED) A semiconductor device comprising:
plural pairs of conductor layers, each pair of conductor layers having wiring patterns and being contained within an insulating layer, wherein:
a semiconductor element is imbedded inside each said insulating layer;
each semiconductor element is electrically connected to a wiring pattern of a respective pair of conductor layers within the respective insulating layer; and
the wiring pattern of each pair of conductor layers is electrically connected, by via holes, to a wiring pattern of a conductor layer of a different pair of conductor layers having wiring patterns and contained within another insulating layer.

#11/c
Am dt
J. Miller
3/21/03

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